

In the claims:

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1. (Once Amended) An apparatus, comprising:
a plurality of bond pads configured in an array;
a first plurality of driver cells located nearer to a nearest die edge than the plurality of bond pads; and
a second plurality of driver cells located farther from the nearest die edge than the plurality of bond pads.

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3. (Once Amended) The apparatus of claim 2, further comprising a plurality of pre-drive cells located farther from the nearest die edge than the second plurality of driver cells.

9. (Once Amended) A semiconductor device, comprising:
a die including

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a plurality of bond pads configured in an array,
a first plurality of driver cells located nearest to a nearest die edge than the plurality of bond pads, and
a second plurality of driver cells located farther from the nearest die edge than the plurality of bond pads; and
a lead frame coupled the plurality of bond pads by a plurality of bond wires.

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11. (Once Amended) The semiconductor device of claim 10, further comprising a plurality of pre-drive cells located farther from the nearest die edge than the second plurality of driver cells.